

(0.635 mm) .025"

QTS SERIES

# HIGH-SPEED GROUND PLANE HEADER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com/QTS](http://www.samtec.com/QTS)

**Insulator Material:**  
Liquid Crystal Polymer  
**Contact Material:**  
Phosphor Bronze

**Plating:**  
Au or Sn over  
50  $\mu$ " (1.27  $\mu$ m) Ni  
**Current Rating:**  
Contact:  
1.8 A per pin  
(2 pins powered)  
Ground Plane:  
23.1 A per ground plane  
(1 ground plane powered)  
**Operating Temp:**  
-55 °C to +125 °C  
**Voltage Rating:**  
285 VAC

**Max Cycles:**

100

**RoHS Compliant:**

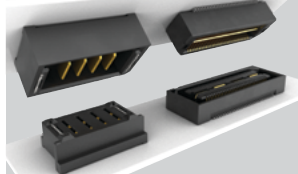
Yes

**Board Mates:**  
QSS

**Cable Mates:**  
SQCD

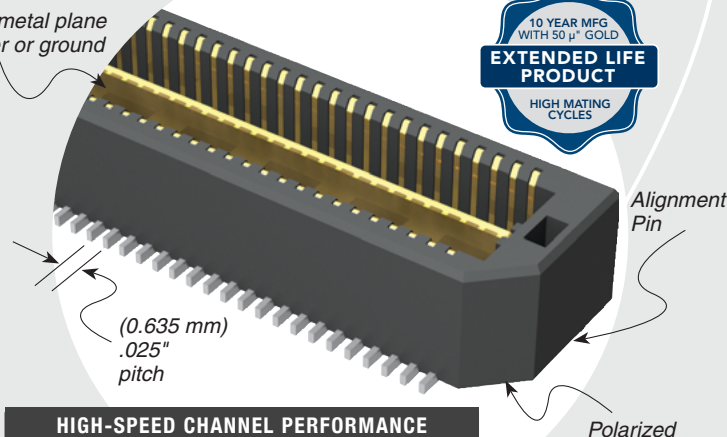
**Standoffs:**  
SO

## POWER/SIGNAL APPLICATION



Compatible with  
UMPT/UMPS for flexible  
two-piece power/signal solutions

Integral metal plane  
for power or ground



## HIGH-SPEED CHANNEL PERFORMANCE

QTS/QSS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com)  
or contact [SIG@samtec.com](mailto:SIG@samtec.com)

**25**  
G b p s

## PROCESSING

**Lead-Free Solderable:**  
Yes

**SMT Lead Coplanarity:**  
(0.10 mm) .004" max (025-075)

**Board Stacking:**  
For applications requiring more  
than two connectors per board  
contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of  
recognitions see  
[www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
- 30  $\mu$ " (0.76  $\mu$ m) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount

**Note:**  
Some lengths, styles and  
options are non-standard,  
non-returnable.

QTS — NO. OF POSITIONS PER ROW — LEAD STYLE — PLATING OPTION — D — A — OTHER OPTION

—025, —050, —075  
(50 total positions per bank)

Specify  
LEAD  
STYLE  
from  
chart.

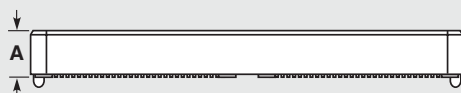
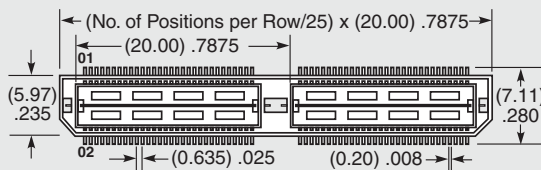
—F  
= Gold Flash on Signal Pins  
and Ground Plane,  
Matte Tin on tails

—L  
= 10  $\mu$ " (0.25  $\mu$ m) Gold on  
Signal Pins and Ground Plane,  
Matte Tin on tails

—C\*  
= Electro-Polished Selective  
50  $\mu$ " (1.27  $\mu$ m) min Au over  
150  $\mu$ " (3.81  $\mu$ m) Ni on Signal  
Pins in contact area,  
10  $\mu$ " (0.25  $\mu$ m) min Au over  
50  $\mu$ " (1.27  $\mu$ m) Ni on Ground  
Plane in contact area,  
Matte Tin over 50  $\mu$ " (1.27  $\mu$ m)  
min Ni on all solder tails

—K  
= (7.00 mm)  
.275" DIA  
Polyimide film  
Pick &  
Place Pad

—TR  
= Tape & Reel



\*Note: —C Plating passes  
10 year MFG testing

LEAD STYLE	A	MATED HEIGHT
—01	(4.27) .168	(5.00) .197
—02	(7.26) .286	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.  
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.